

A High-Dynamic-Range W-band Frequency-Conversion IC for Microwave Dual-Conversion Receivers

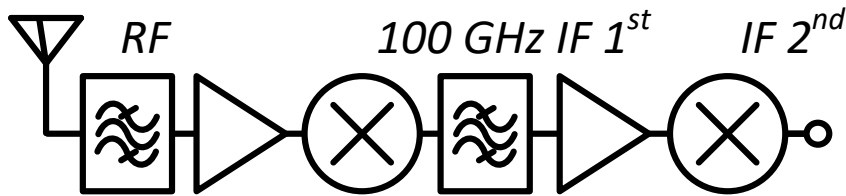
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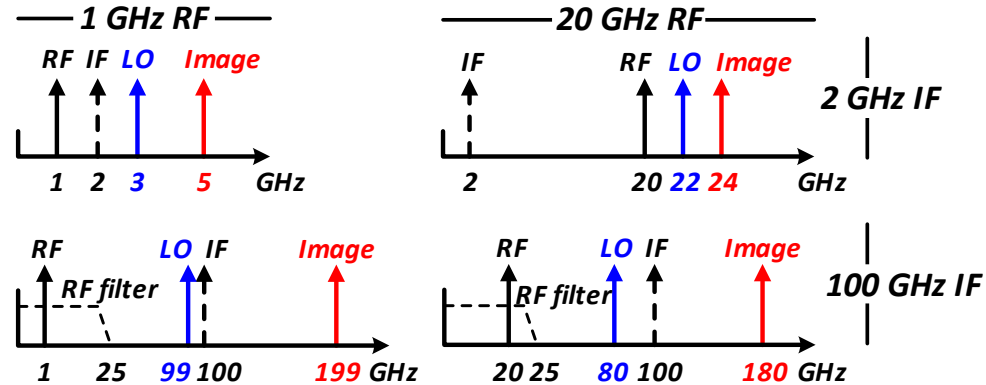
¹University of California at Santa Barbara, CA

²Teledyne Scientific and Imaging, CA

Dual-Conversion Receiver



1-25 GHz RF tuning range



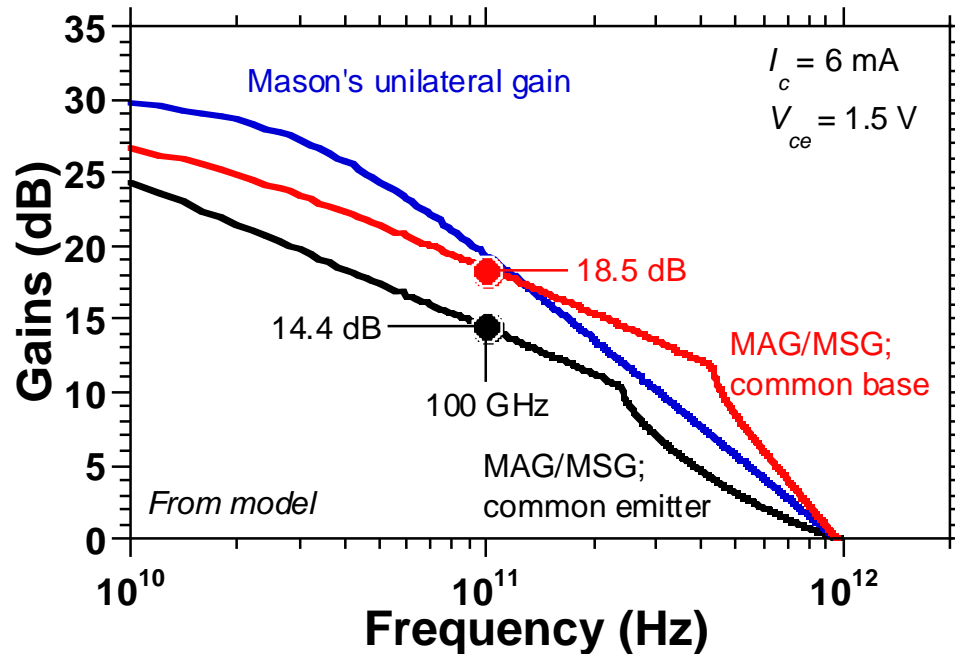
Classical RF architecture: extend to micro/mm-wave frequencies

- Up-convert to 1st IF (100 GHz), down-convert to 2nd IF (or baseband)
- Image response moved out-of-band
- Very wide tuning range, no image response.

Applications:

- Instrumentation
- Wideband surveillance: 1-25 GHz (possibly 1-50 GHz)
- Single IC serving many applications: application-specific LNA + common module

THz HBTs → 1-25 GHz Dual conversion



Teledyne 130 nm InP HBT

1.1 THz f_{max}

CE: 14.4 dB MSG @100 GHz

CB: 18.5 dB MSG @100 GHz

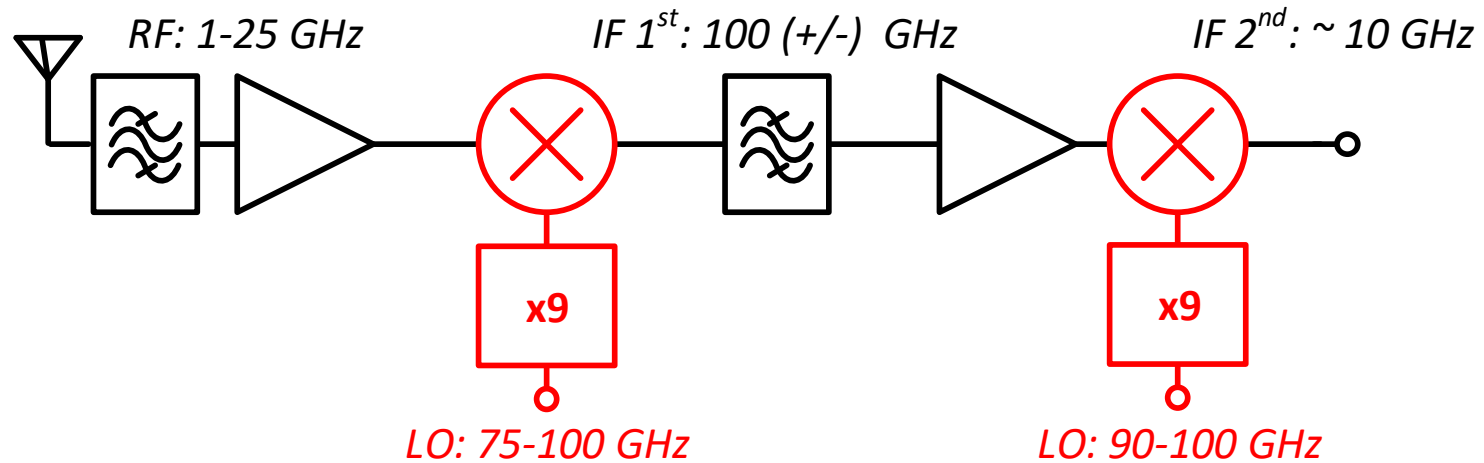
Dual conversion at microwave:

100 GHz 1st IF would enable over 1-60 GHz spur-free tuning

High speed IC technologies: 100 GHz IF feasible

THz transistors enable microwave dual-conversion receivers

Frequency Conversion Blocks



Need high dynamic range & wide tuning range

This presentation: the frequency conversion blocks

High Dynamic Range Mixer

Transistor mixer:

Low IP3

High noise figure

Poor dynamic range

Diode mixer:

High IP3

Lower noise figure

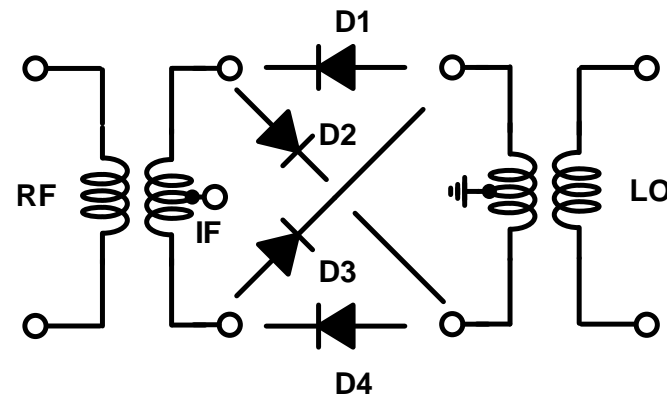
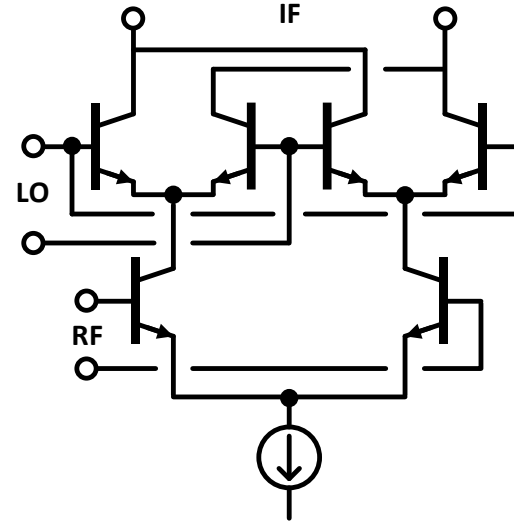
Higher dynamic range

Design challenges:

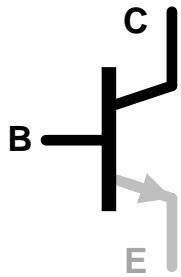
High speed diode

Wide bandwidth balun

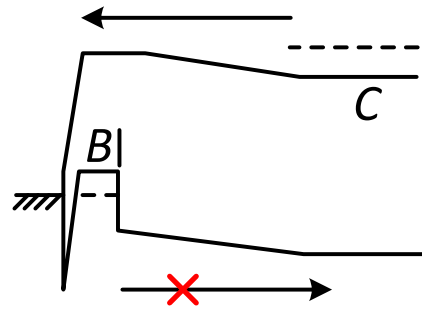
Wide tuning range + high power LO



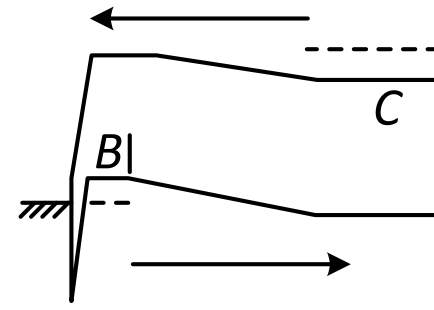
High Speed DHBT BC Diode



DHBT



Band diagram



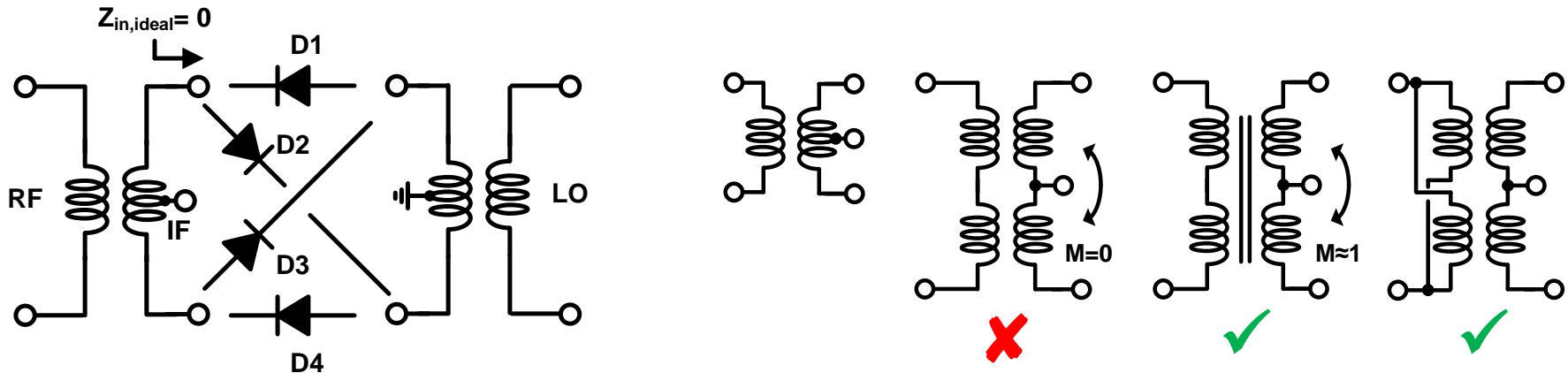
SHBT band diagram

Double-heterojunction base-collector diode

- Hole minority carrier storage is eliminated by large energy barrier to holes
- Electron minority carrier storage time is small

→ Schottky-like high-frequency characteristics

Balun For Diode Mixer



Common-mode impedance $Z_{cm,RF}$ must be zero

IF port is required

Simple center-tapped transformer has wrong Z_{cm}

- Two transformers in *series*.

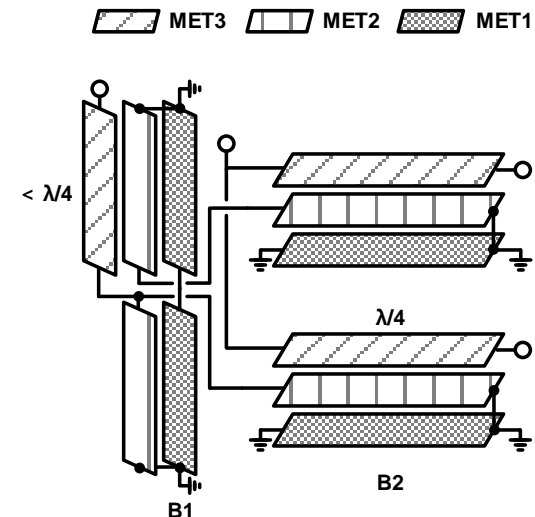
Ferrite loading gives correct Z_{cm} ; can't use on IC

Options: two *parallel* transformers, or balun.

Proposed balun

- Sub-quarter wavelength balun (B1) [3]

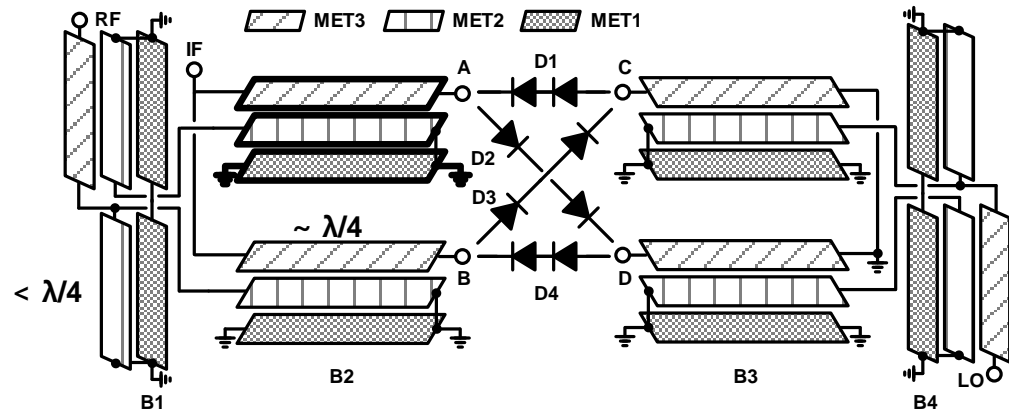
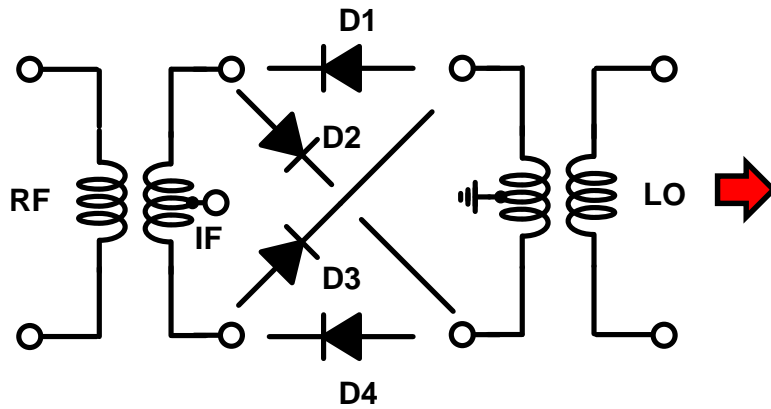
- Section B2 provides the IF port and $Z_{cm,RF}=0$



Proposed balun

[3] H. Park, et al., *IEEE J. Solid-State Circuits* (UCSB)

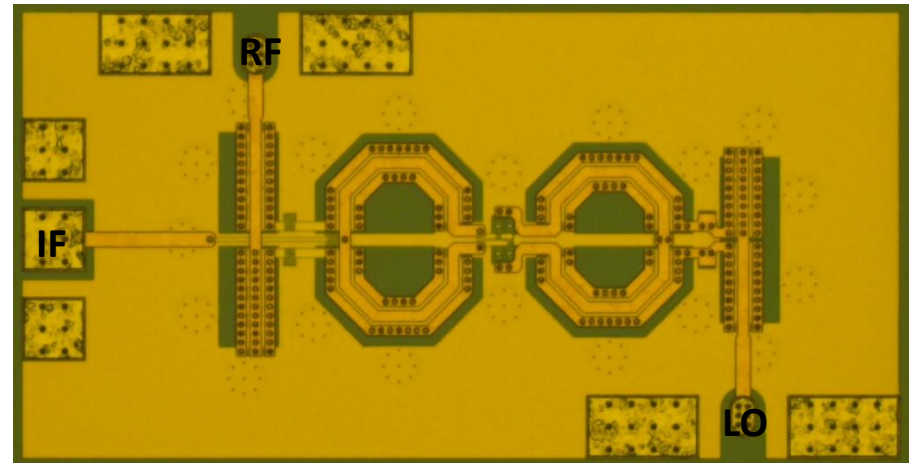
Diode Mixer



Four series-connected BC diode pairs

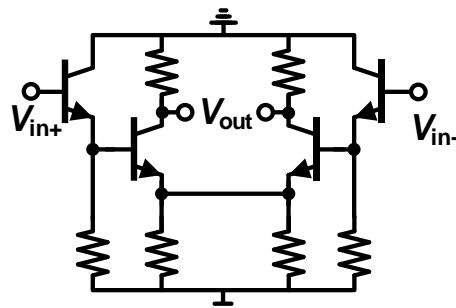
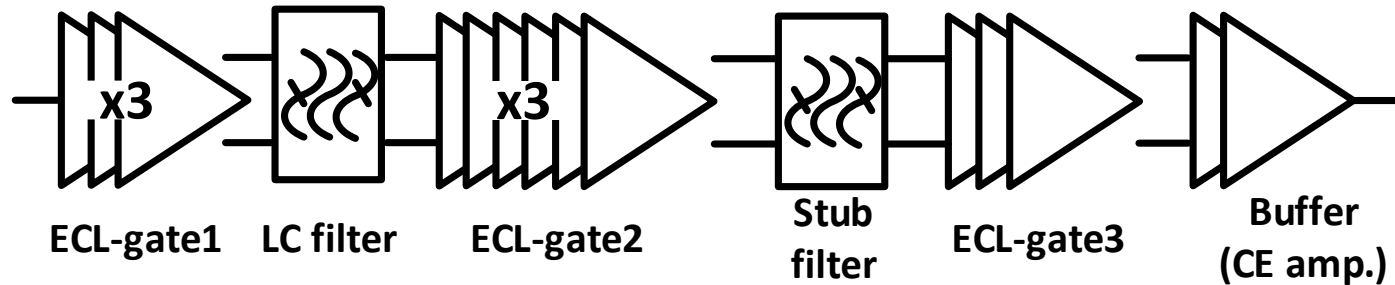
RF and LO baluns

Balun loss < 4 dB over W-band

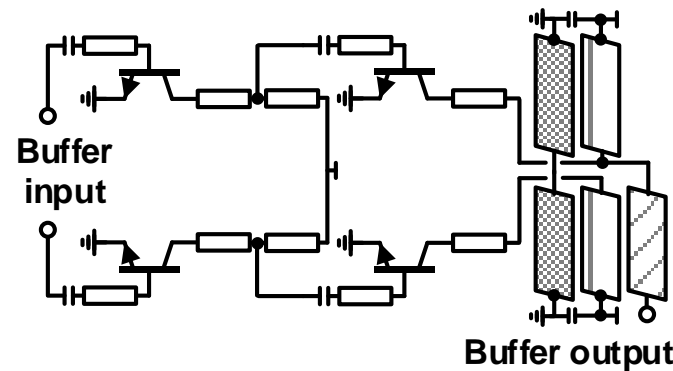


Size: 700 μm x 300 μm (excl. pads)

LO Multiplier Chain



ECL-gate



Buffer

ECL-gates generate squarewave \rightarrow Strong third harmonic, wide bandwidth

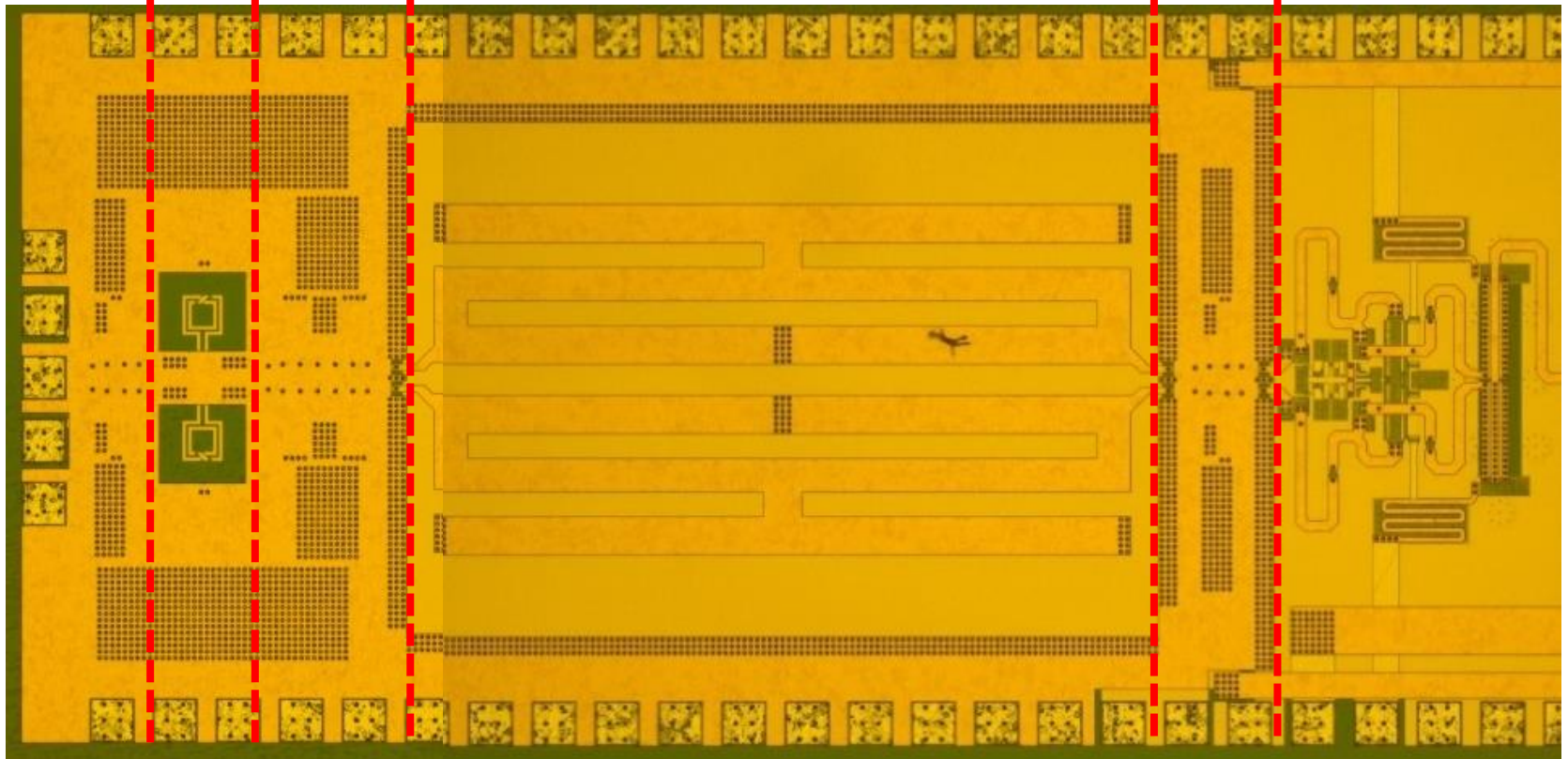
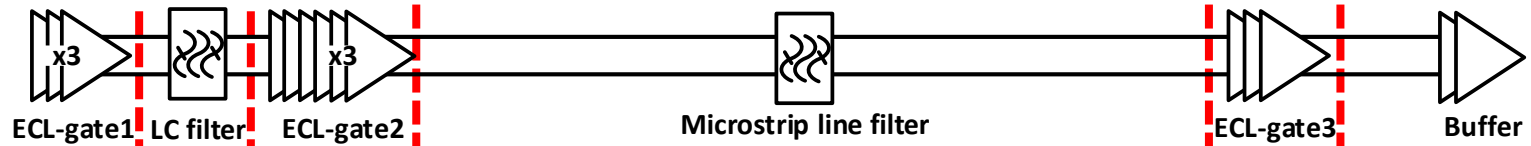
Chebyshev LC filter: 20-34 GHz

Microstrip line bandpass filter: 60-100 GHz

3-stage ECL pre-amplifier

Buffer: two-stage pseudo-differential common-emitter amplifier > 8 dBm

LO Multiplier Chain

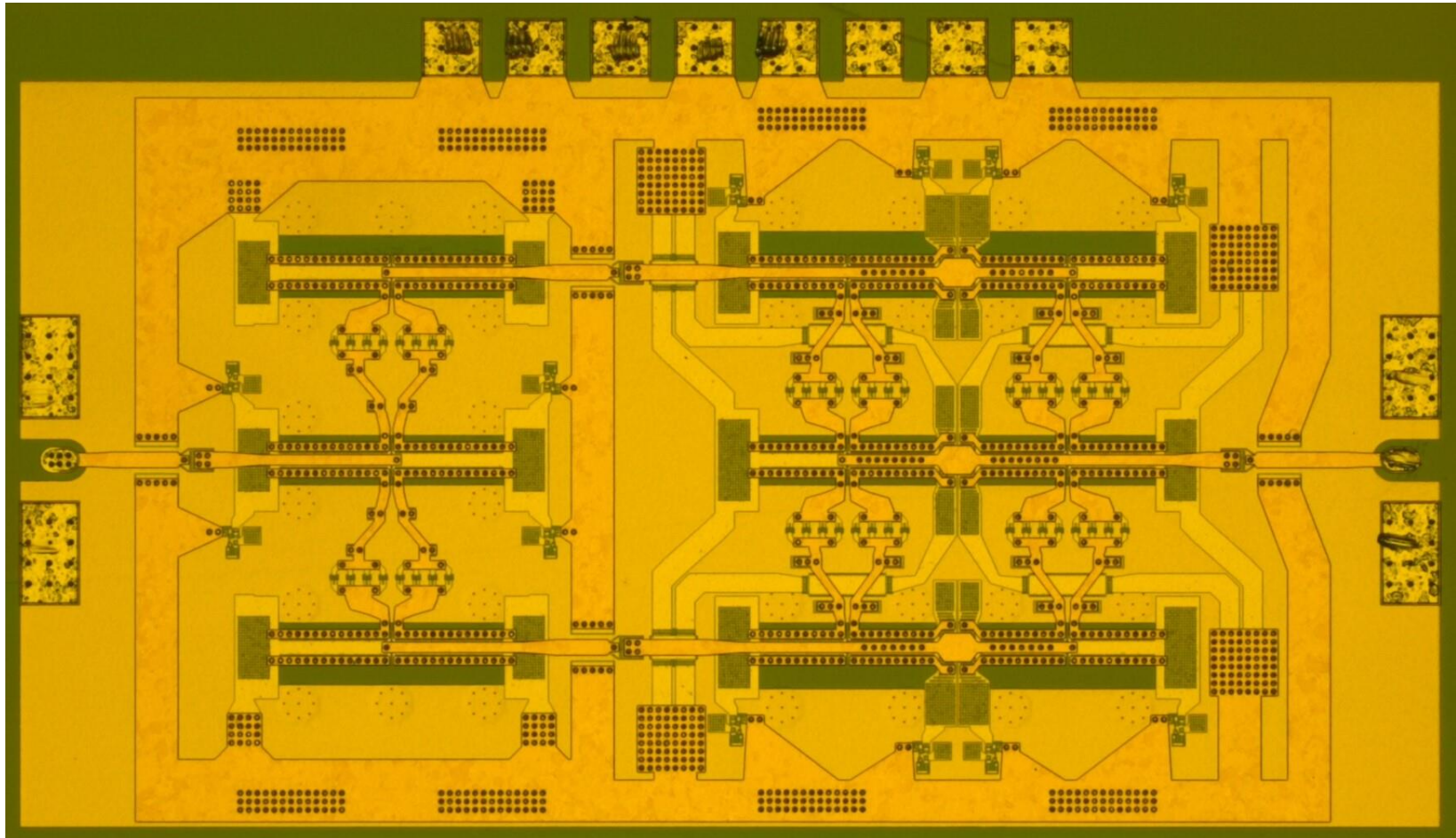


Measured P_{out} : 8-11.5 dBm over 75-105 GHz tuning bandwidth

Power consumption: 270 mA from -4 V supply, 64 mA from 2 V supply

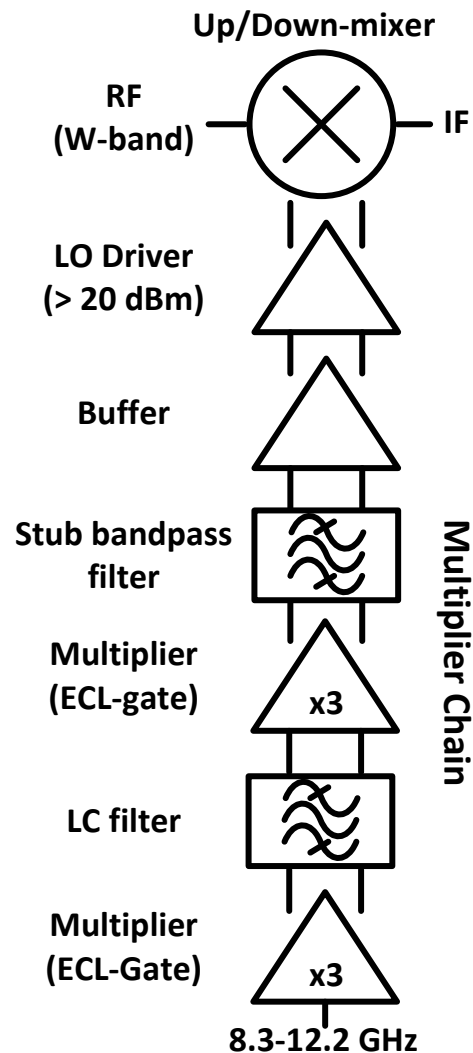
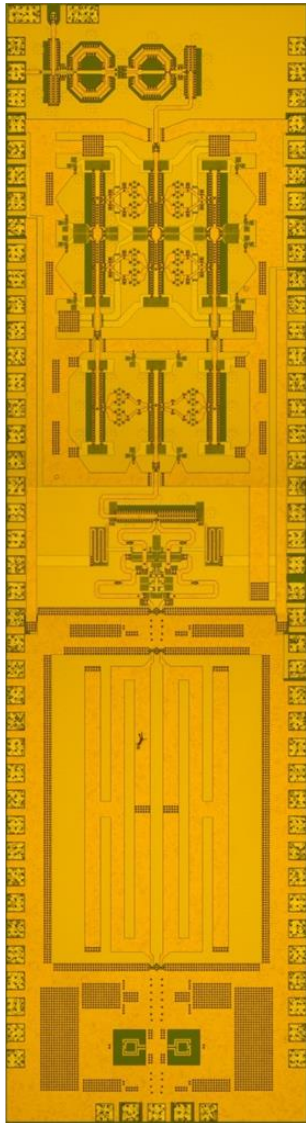
High-Power LO Driver

Wide bandwidth > 60-100 GHz, > 19 dBm output power



R. Maurer, et al., "Ultra-wideband mm-Wave InP Power Amplifiers in 130nm InP HBT Technology," in *2016 IEEE CSICS*
 *Presented in SESSION F on Oct. 25

Frequency Conversion IC



Integrated frequency conversion IC

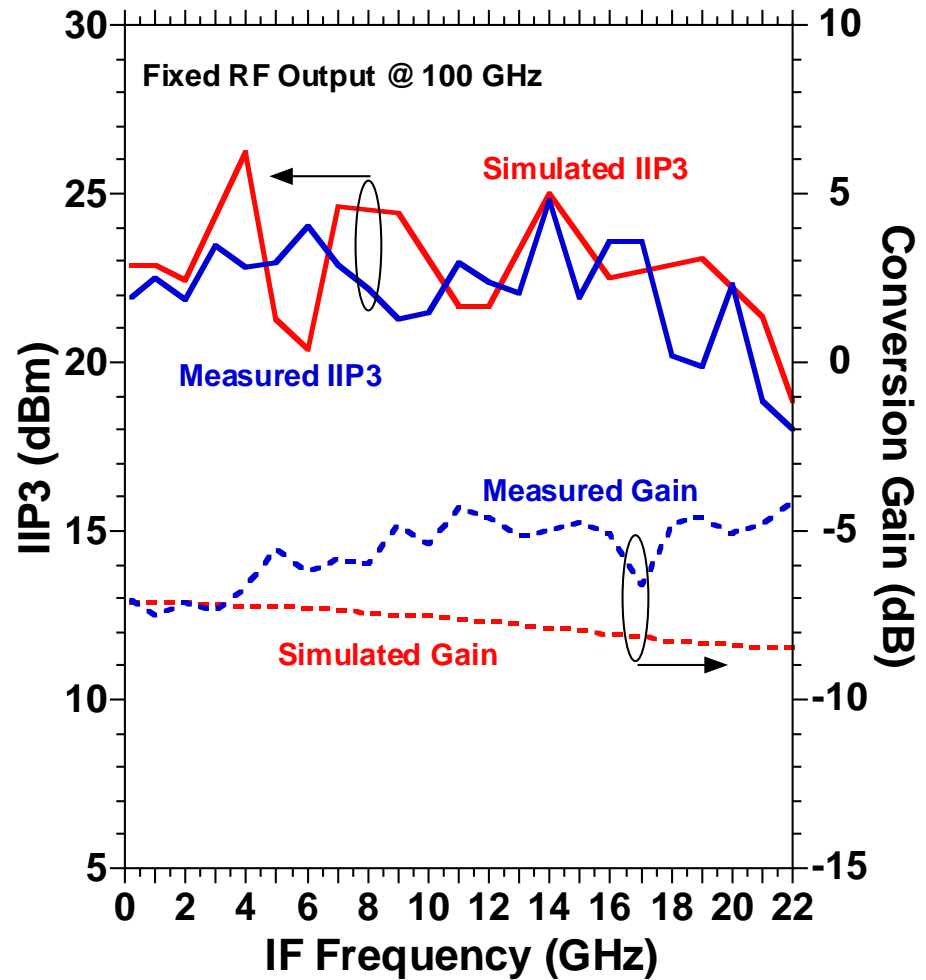
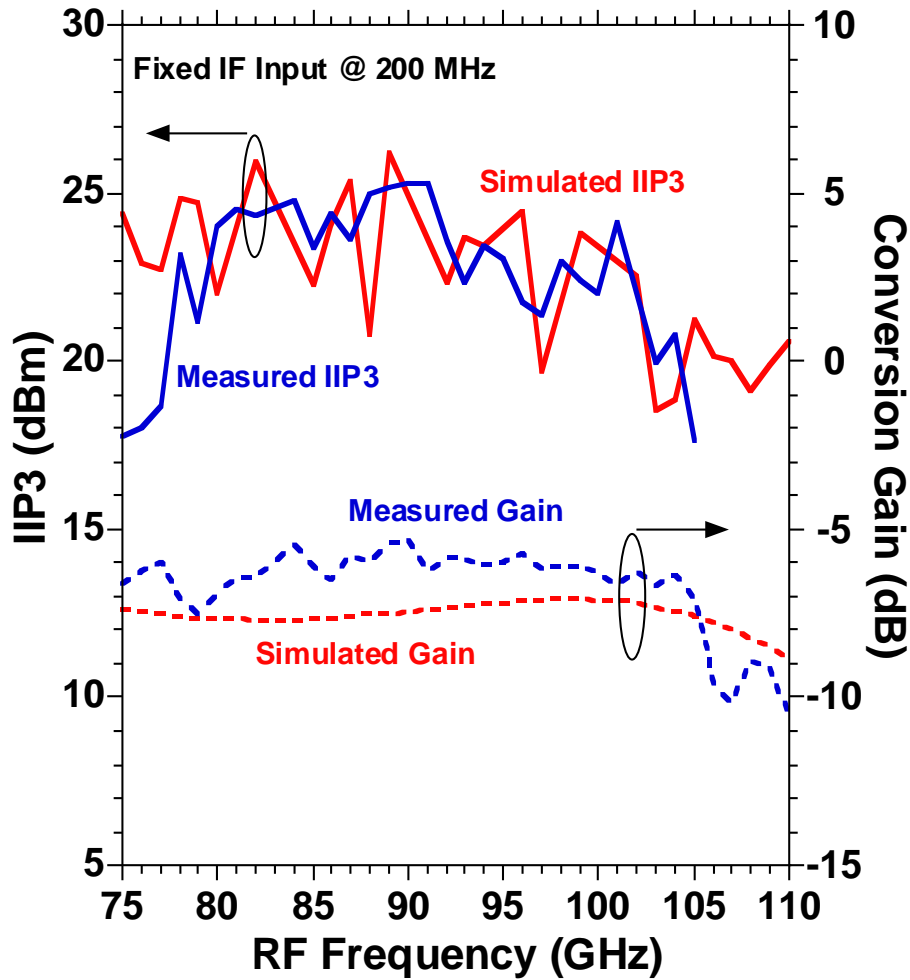
- Diode mixer
- High power LO driver
- x9 multiplier chain
- **136** emitter fingers
- **326** passive components

Total power consumption: 2 W

- Multiplier chain and LO driver

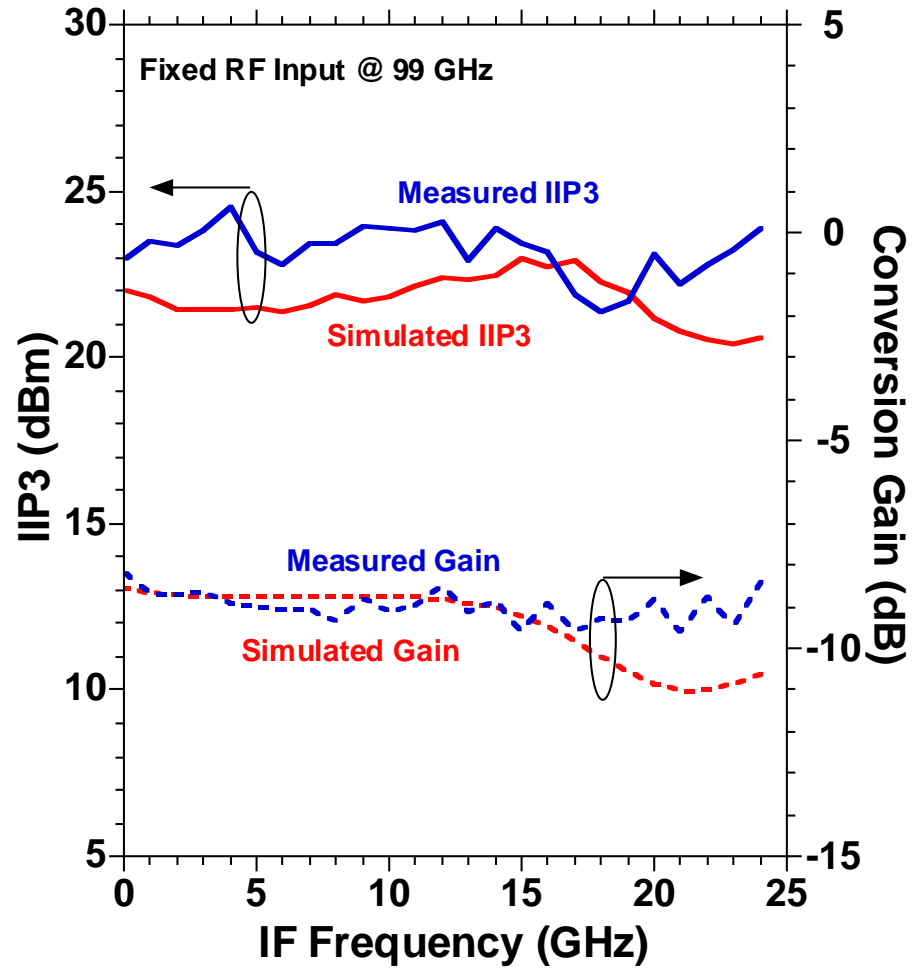
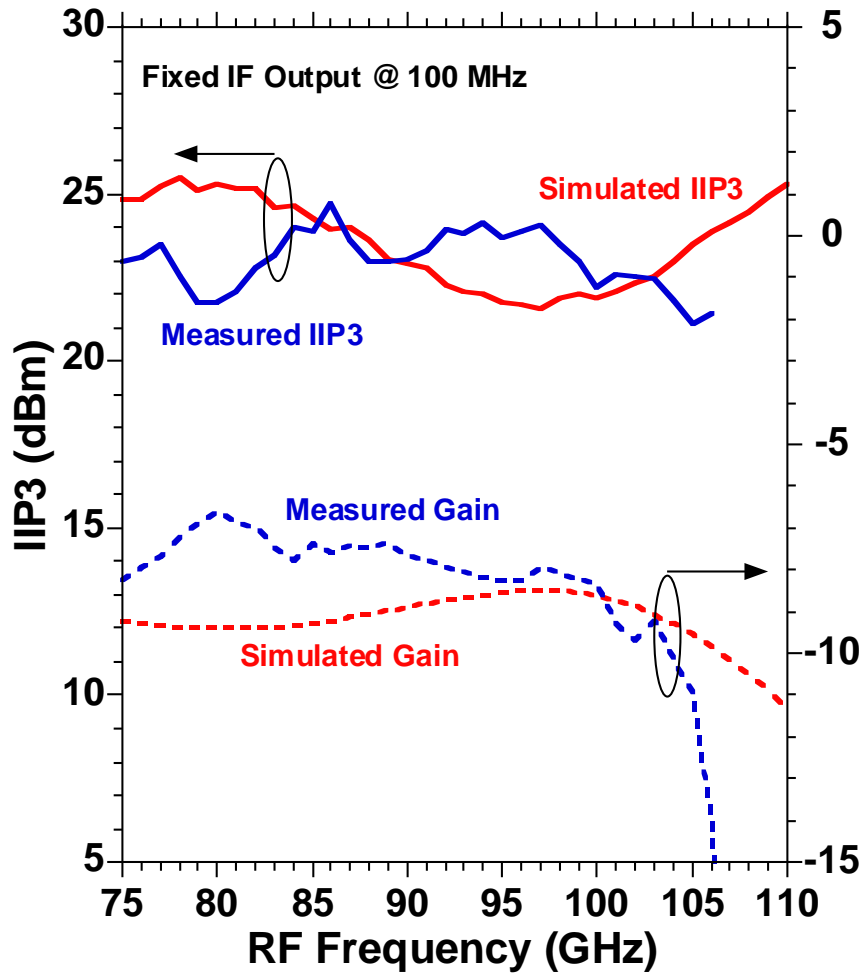
Size: 4300 um x 1160 um

Up-Conversion Measurements



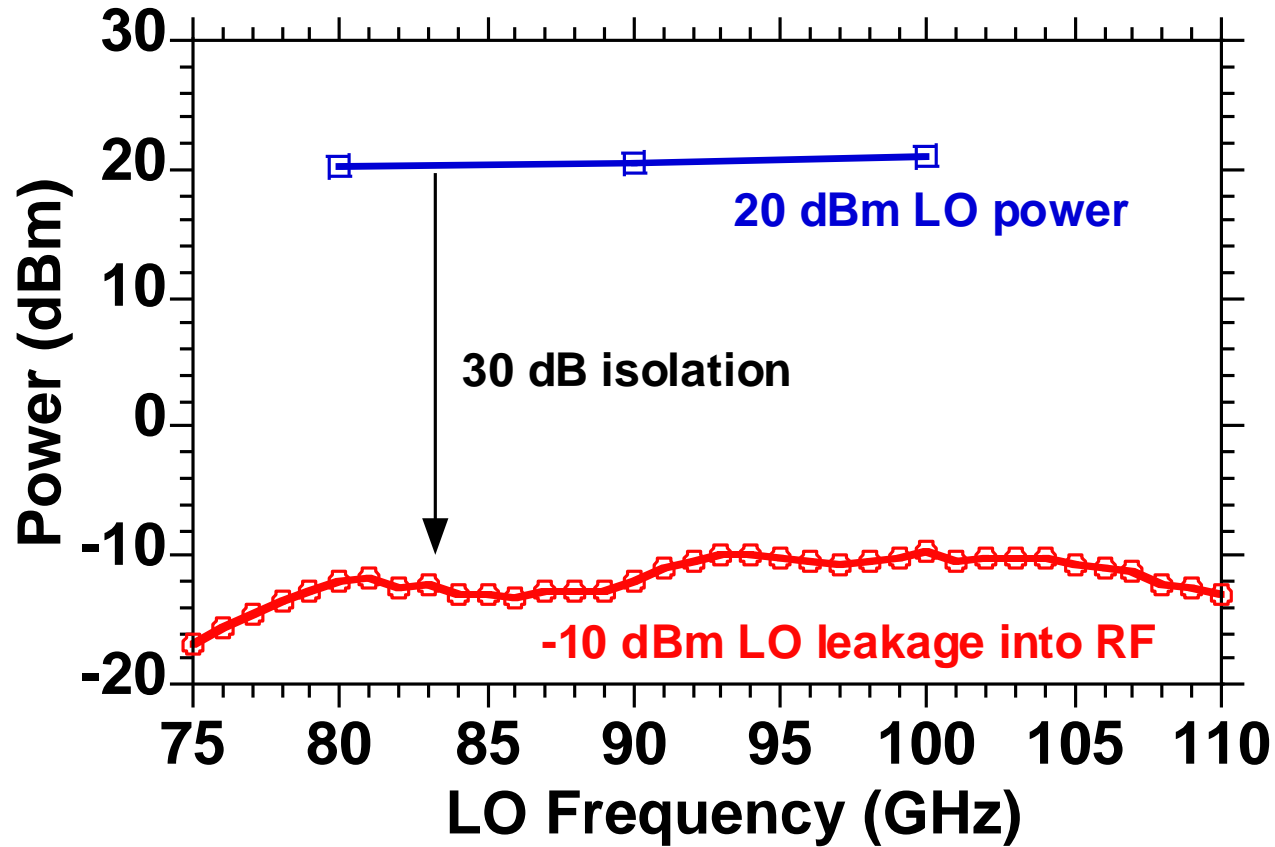
7 dB conversion loss and 23 dBm IIP3

Down-Conversion Measurements



8 dB conversion loss and 23 dBm IIP3

LO Leakage



W-band frequency conversion IC

Dual conversion: classic widely-tunable RF receiver design
Extend to microwave (3-30 GHz) → Need ~100 GHz IF

Dual conversion: feasible with wideband (THz) transistors

100 GHz signal frequency is only 10% of transistor f_{\max}

Enable high-dynamic-range mixers (& amps: next talk)

9:1, 75-100 GHz LO multiplier using digital techniques (ECL-gates)

Present frequency conversion IC

High dynamic range (7-8 dB loss \approx noise figure, 23 dBm IIP3)

Very wide tuning LO (1-25 GHz \leftrightarrow 76-100 GHz)

Application: 1-25 GHz dual-conversion receiver

Complex IC in a 1 THz IC technology

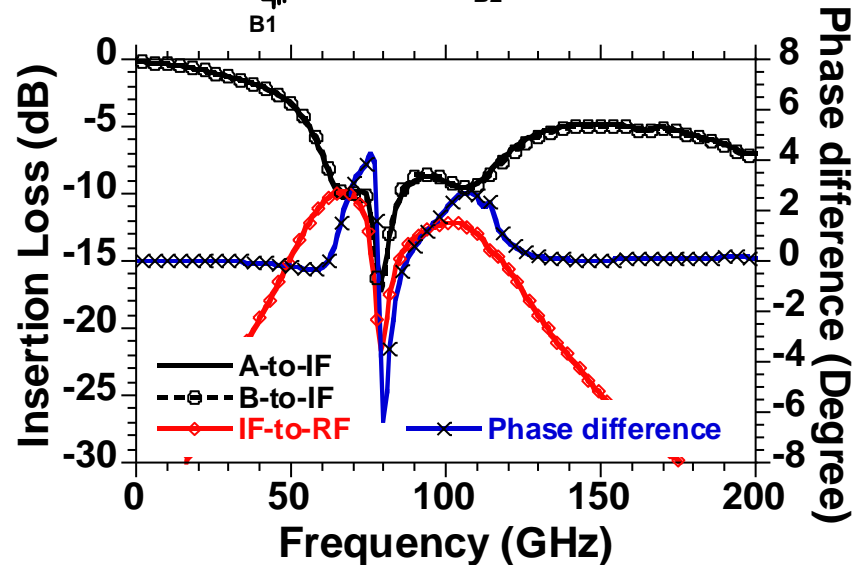
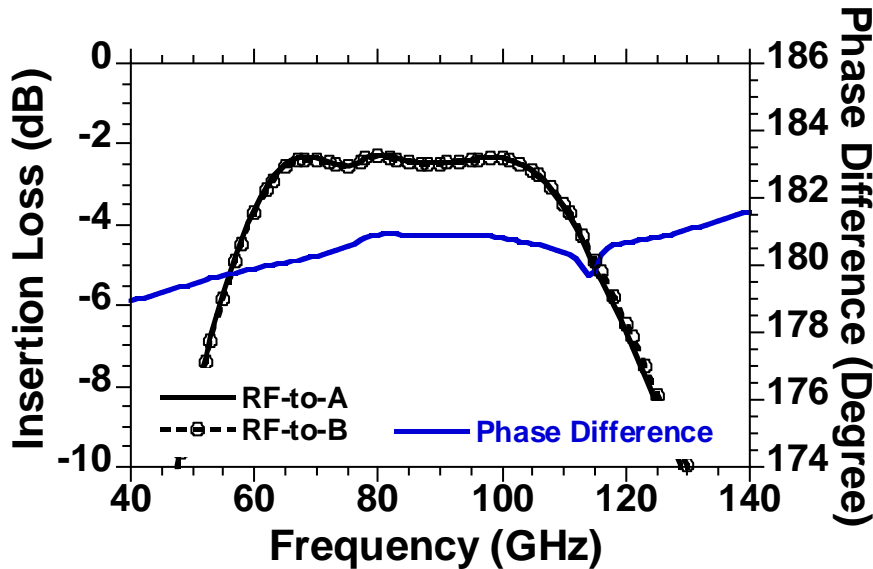
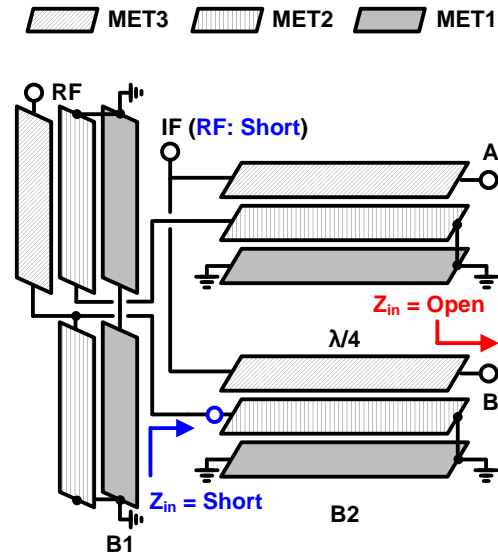
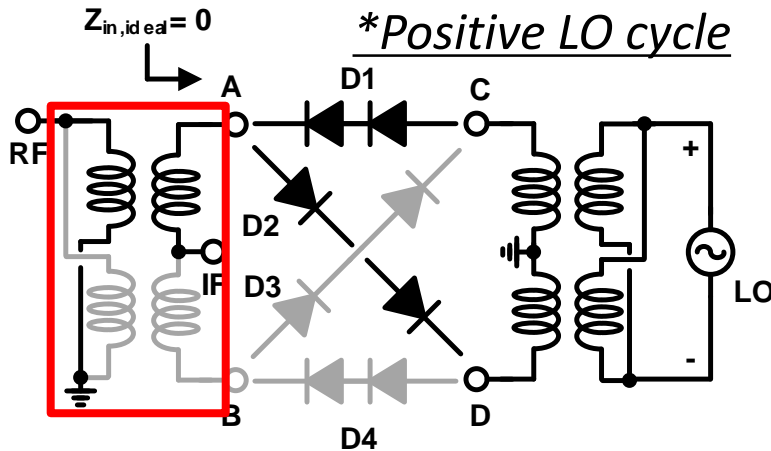
136 HBT emitter fingers, 326 passive components, 16 cascaded stages

1st pass: good correlation between simulation & measurement

We thank Teledyne Scientific & Imaging for IC fabrication

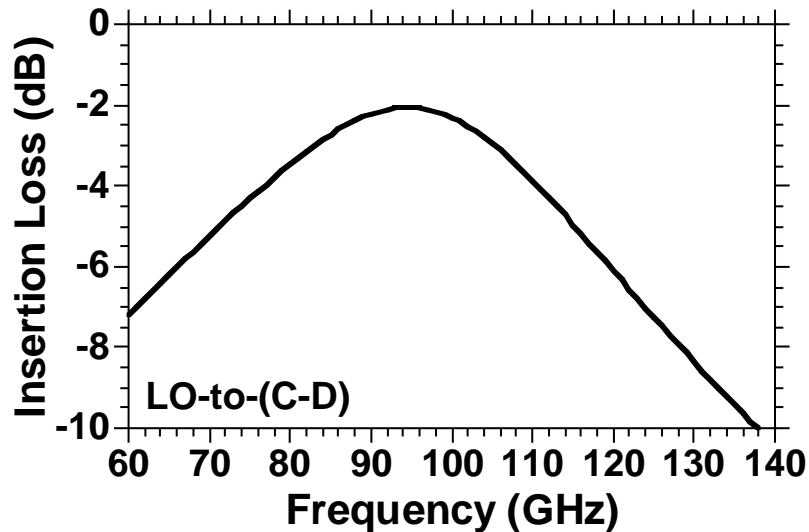
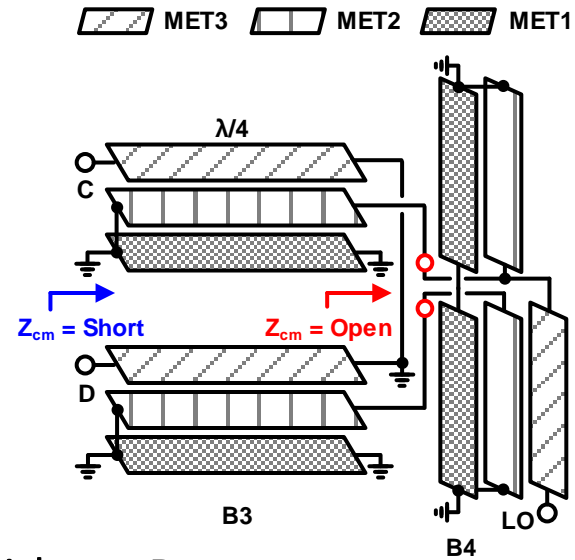
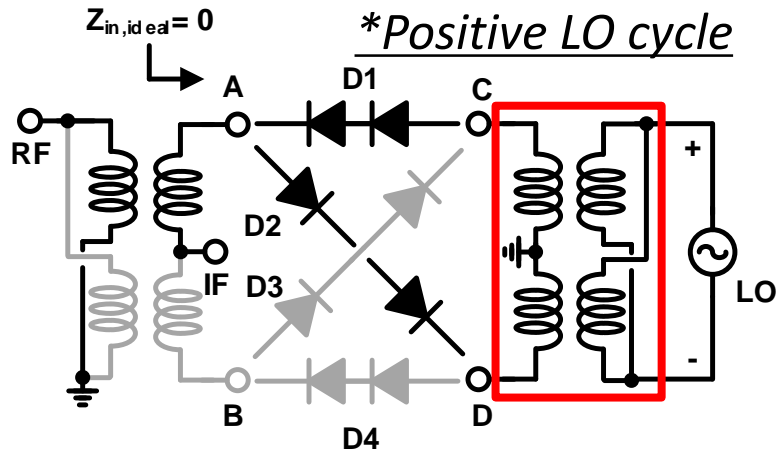
Thank you

RF Balun Design



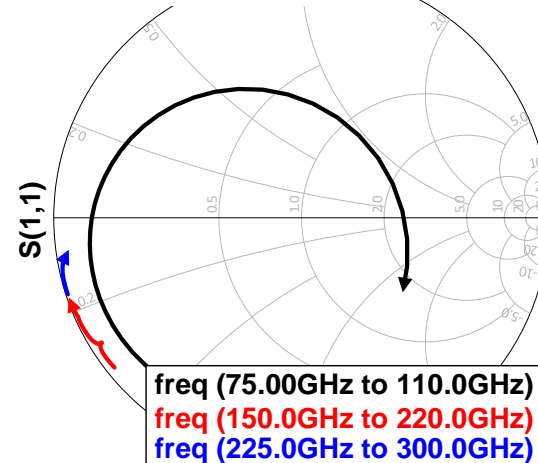
Insertion loss < 3.5 dB, phase error < 4° over W-band

LO Balun Design

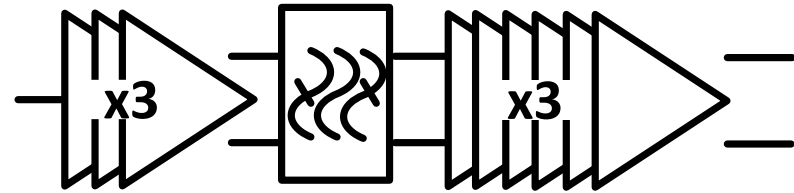
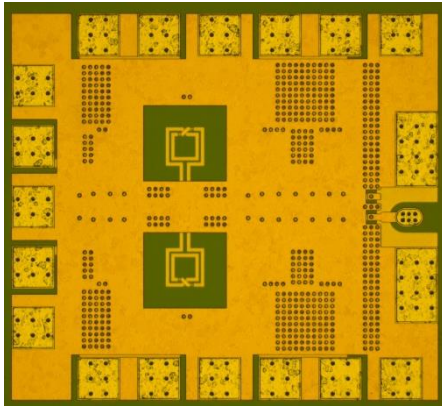


2-4 dB insertion loss over W-band

Z_{in} without $R_{on,diode}$

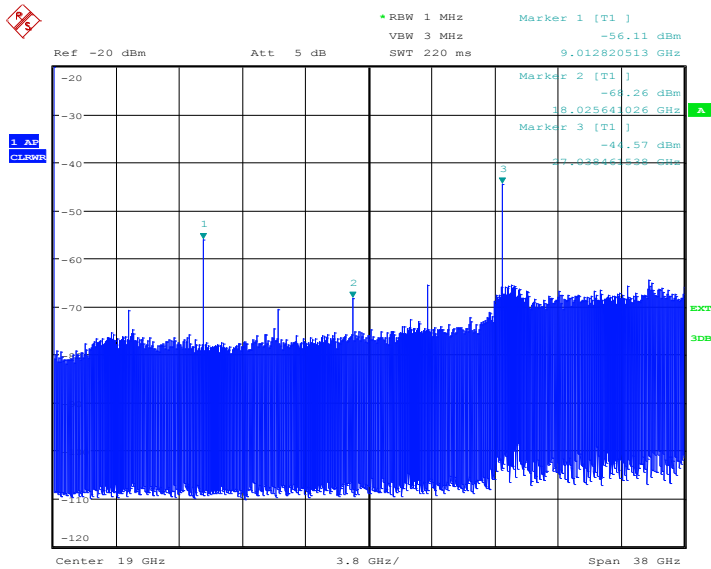


Multplier x3

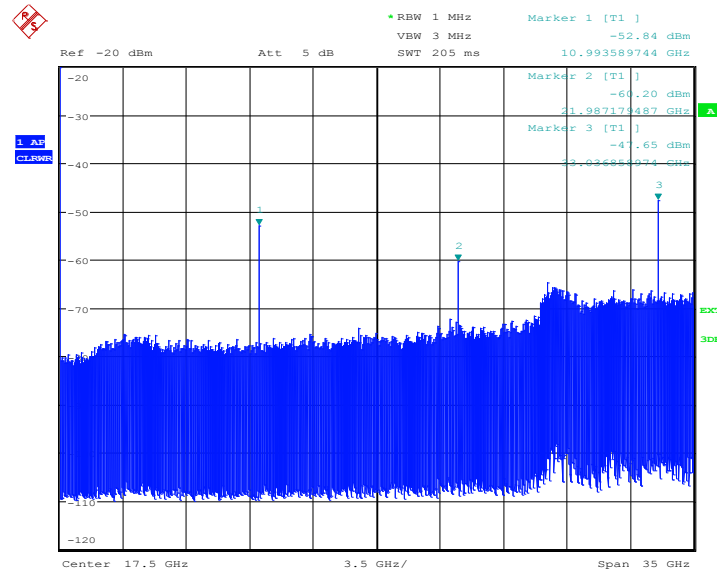


ECL-gate1 LC filter ECL-gate2

*Ground plane: top metal layer



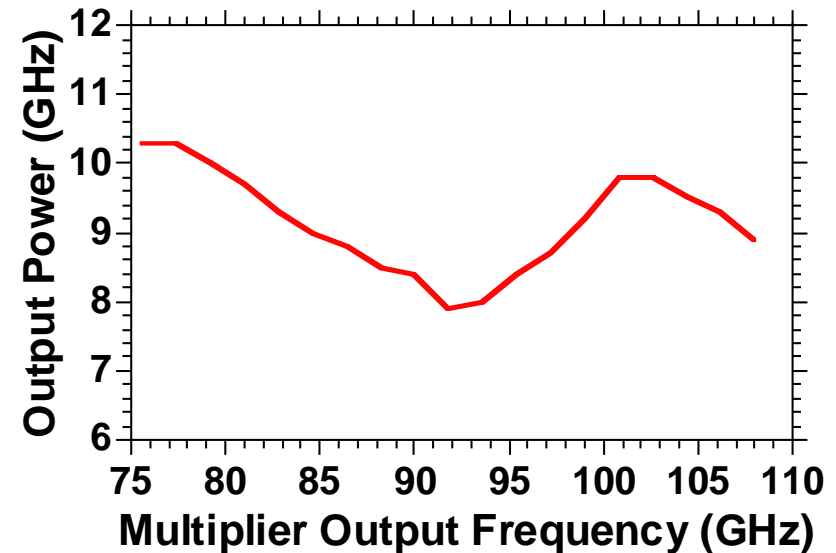
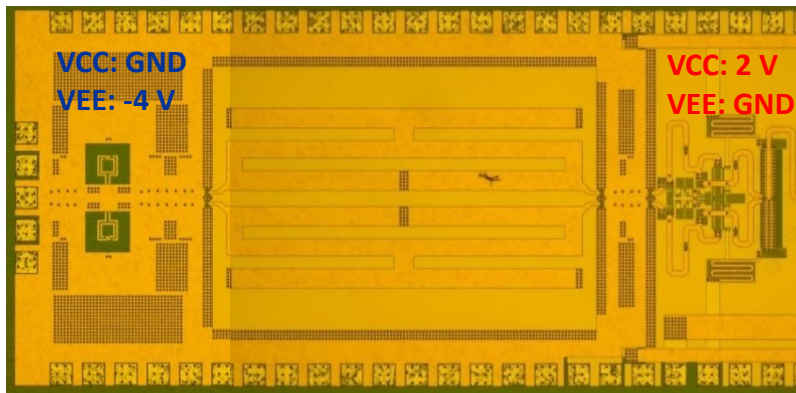
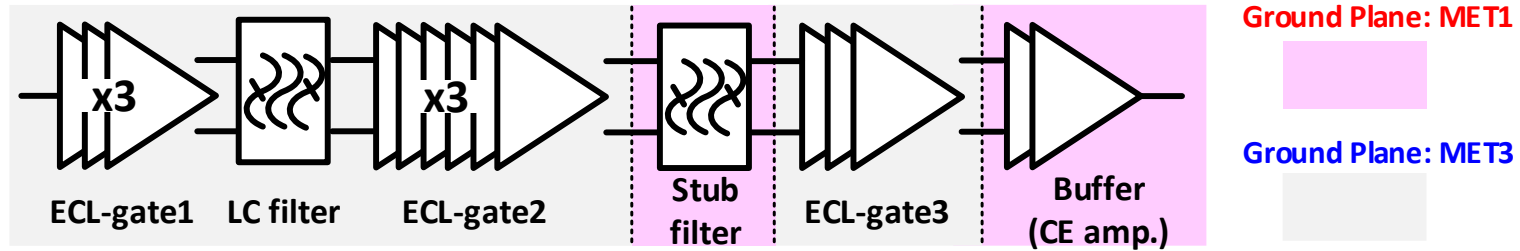
Input @ 9.0 GHz



Input @ 11.0 GHz

*Cable loss is not calibrated

LO Multiplier Chain



Measured $P_{out} > 8$ dBm

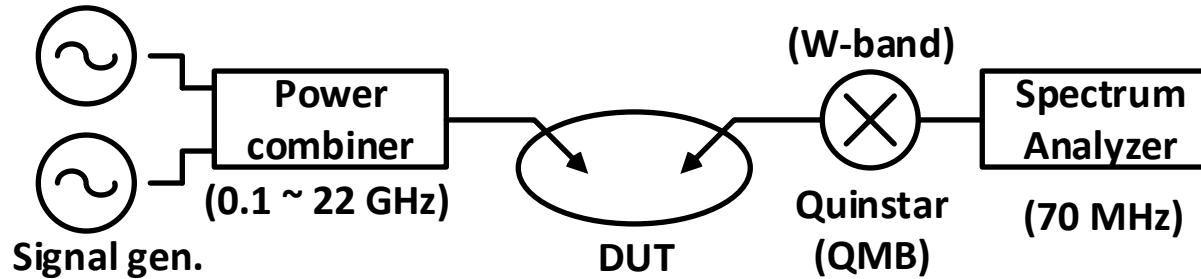
Power consumption

- V_{EE} : 270 mA @ -4 V

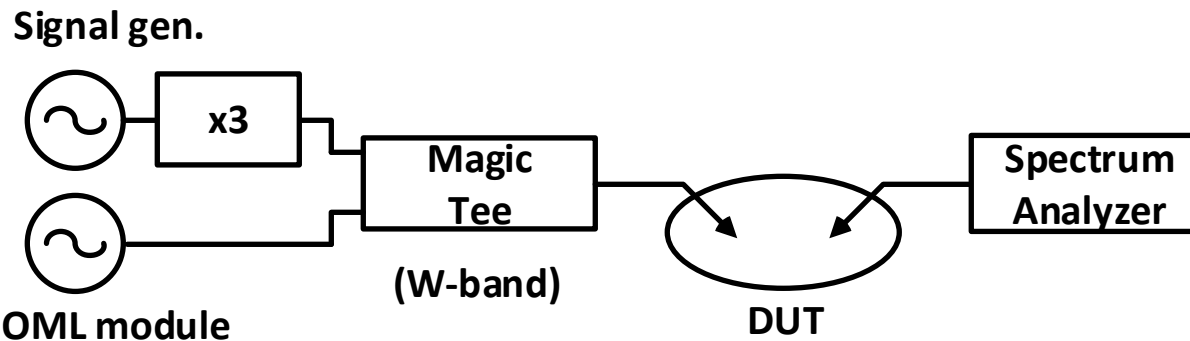
- V_{CC} : 64 mA @ 2 V

Measurement Setup

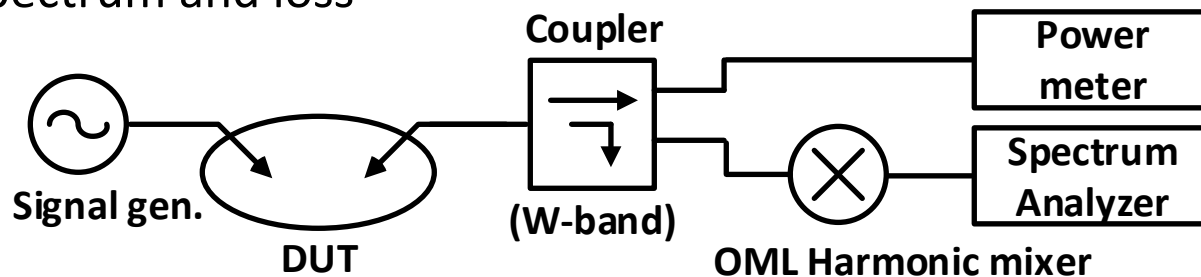
IIP3 (up-conversion)



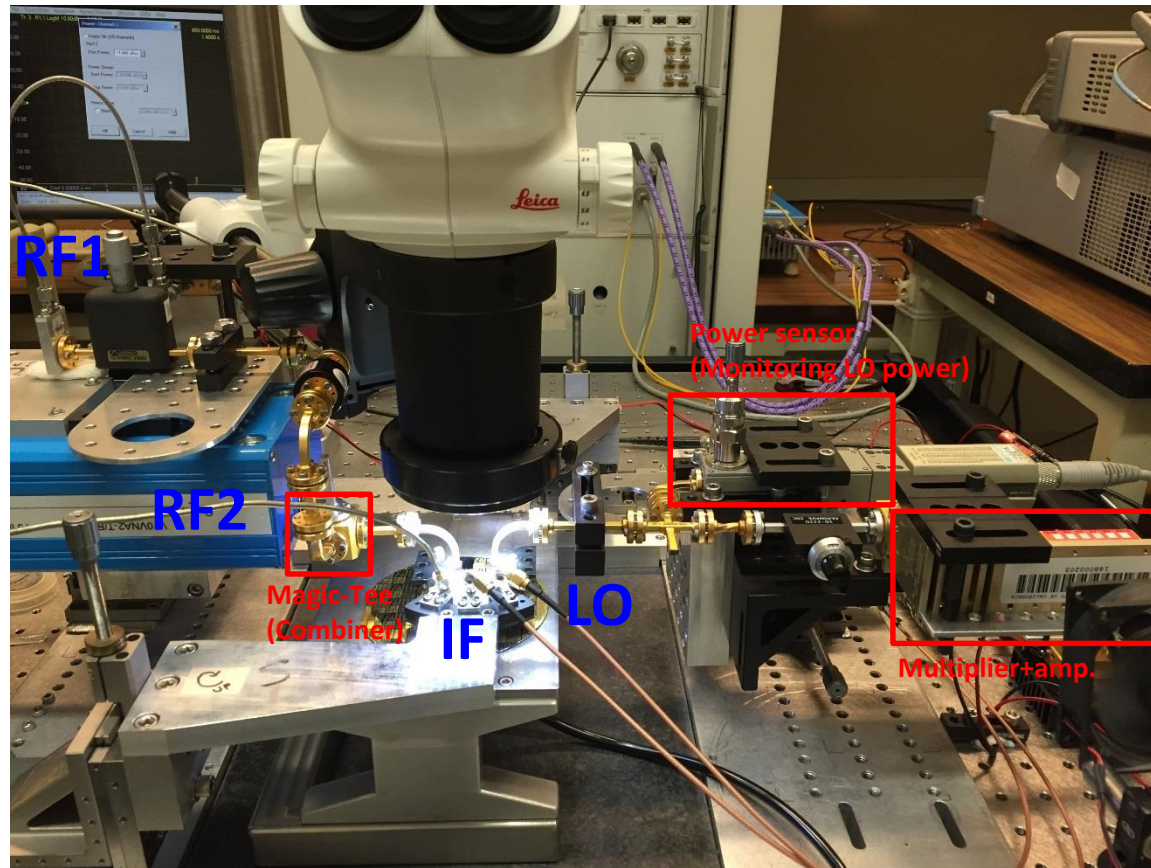
IIP3 (down-conversion)



W-band spectrum and loss



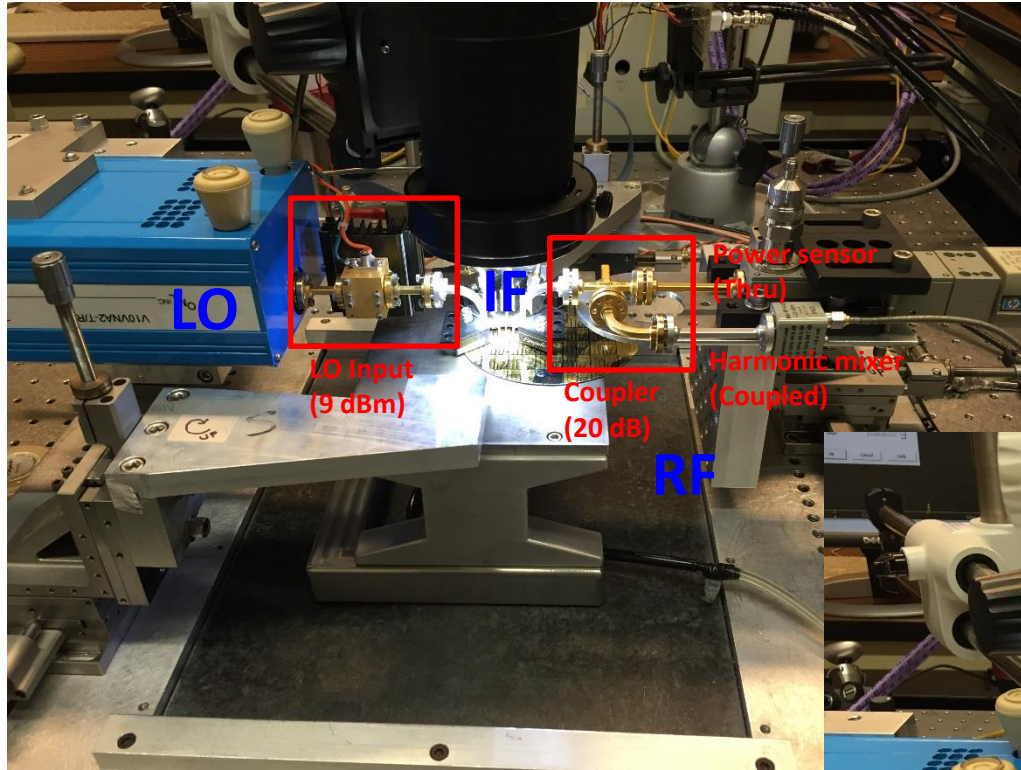
IIP3 Measurement Setup



Up-conversion

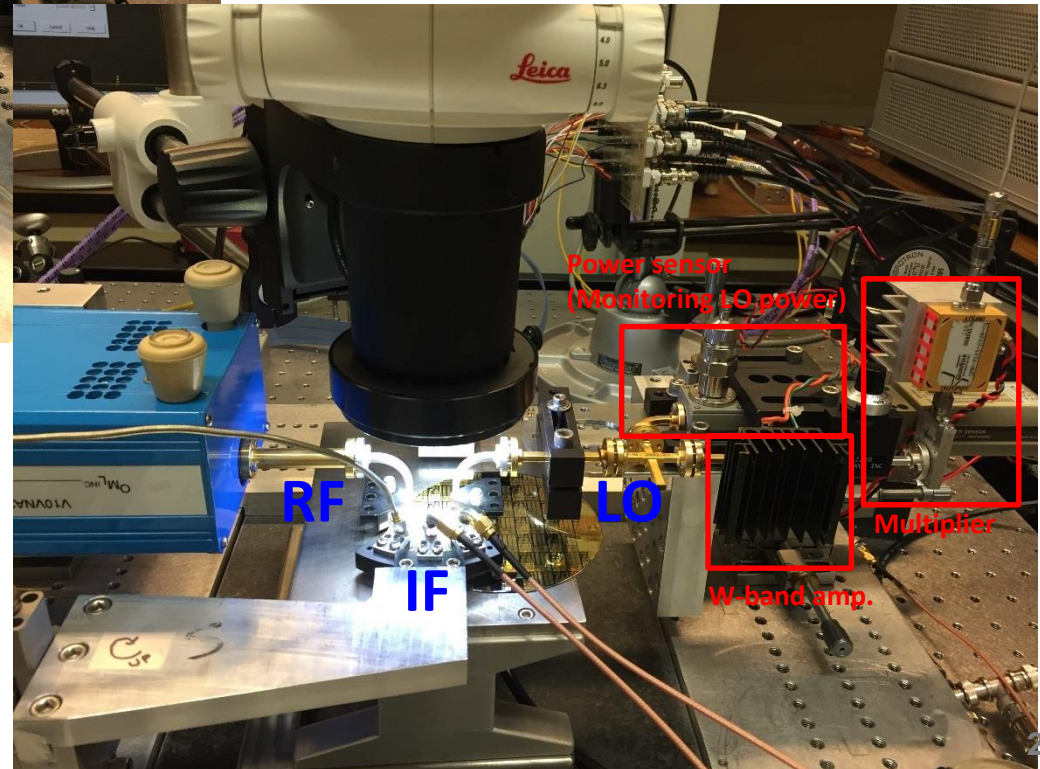
Measurement Setup

Spectrum and gain

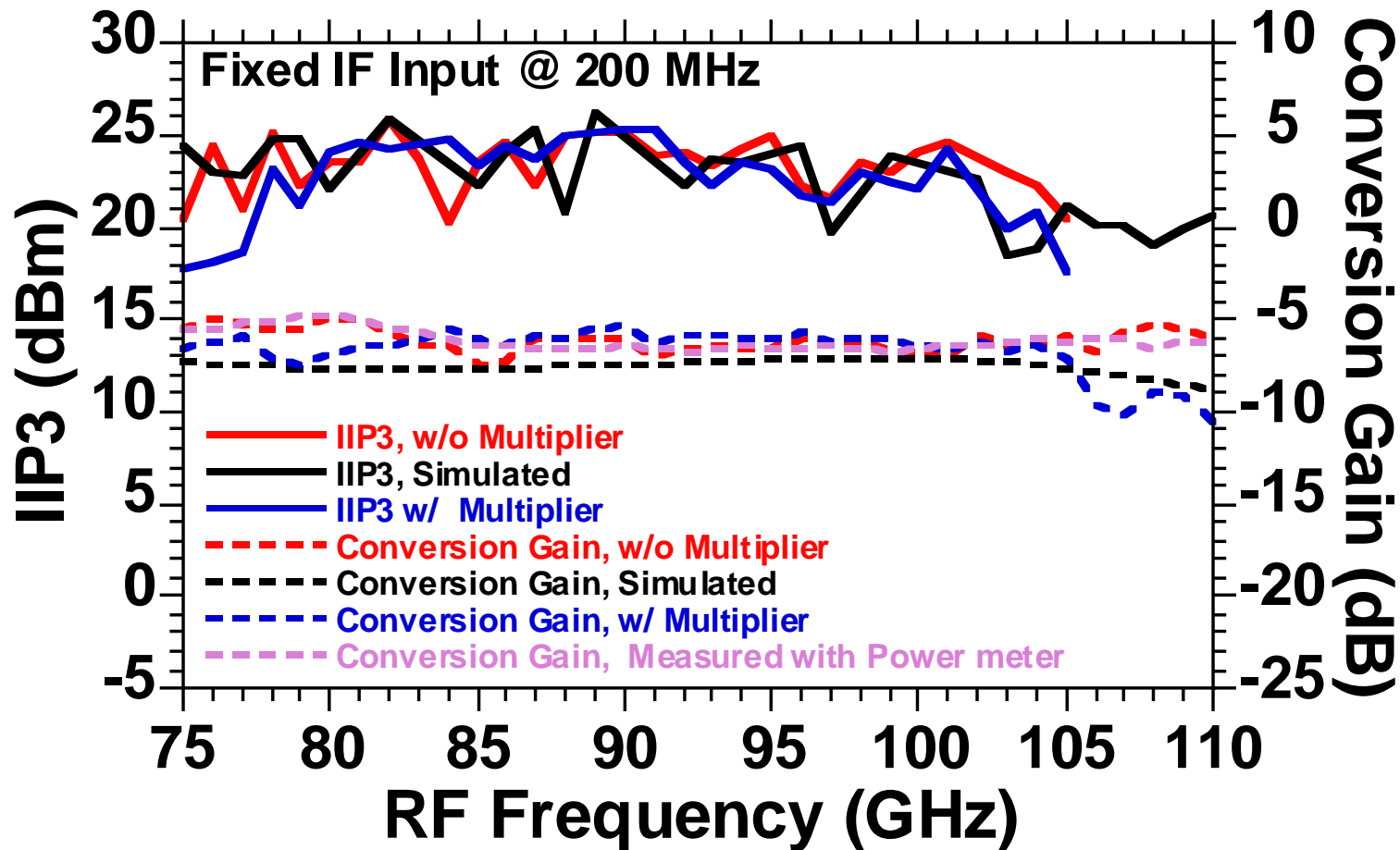


Up-conversion

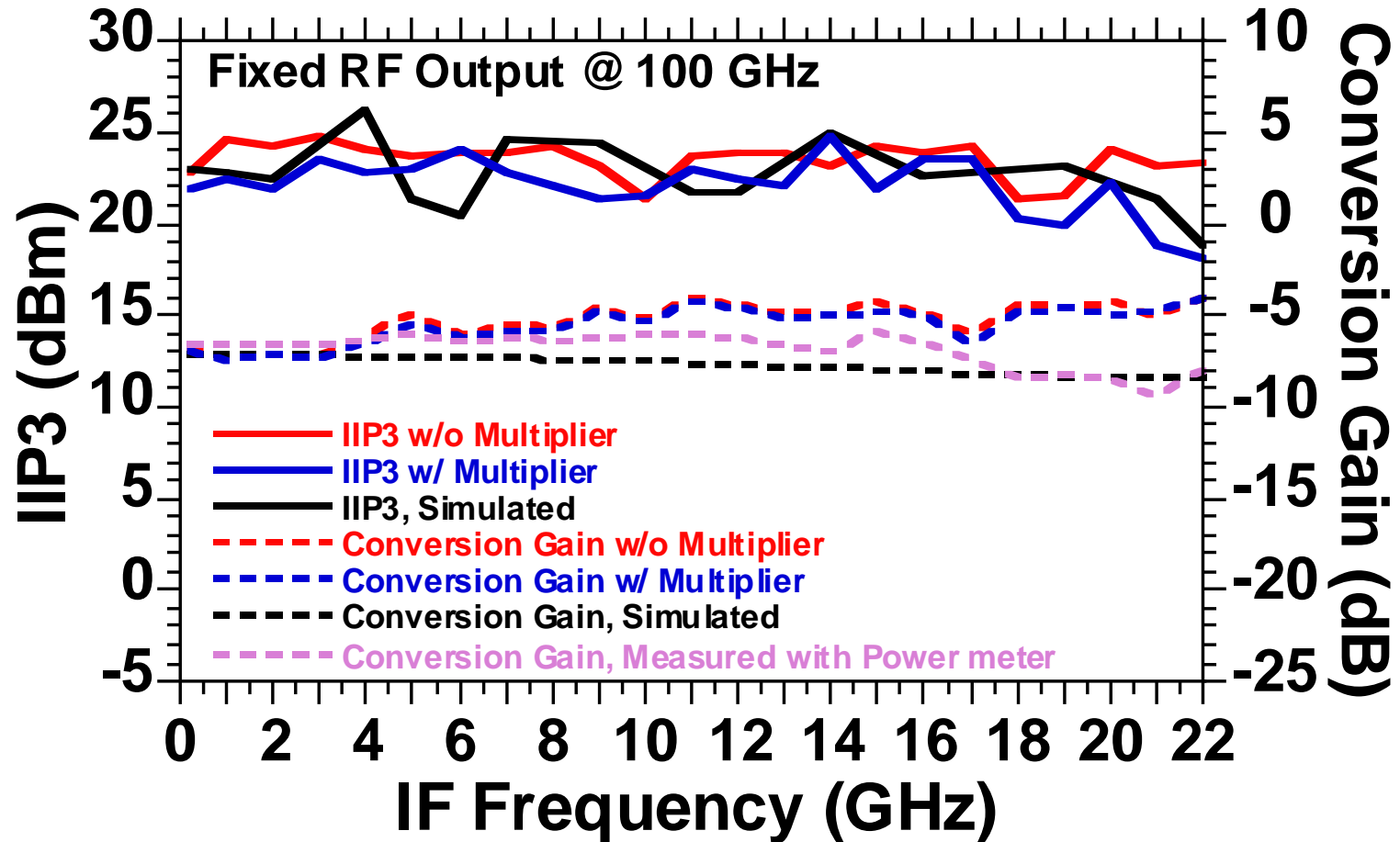
Down-conversion



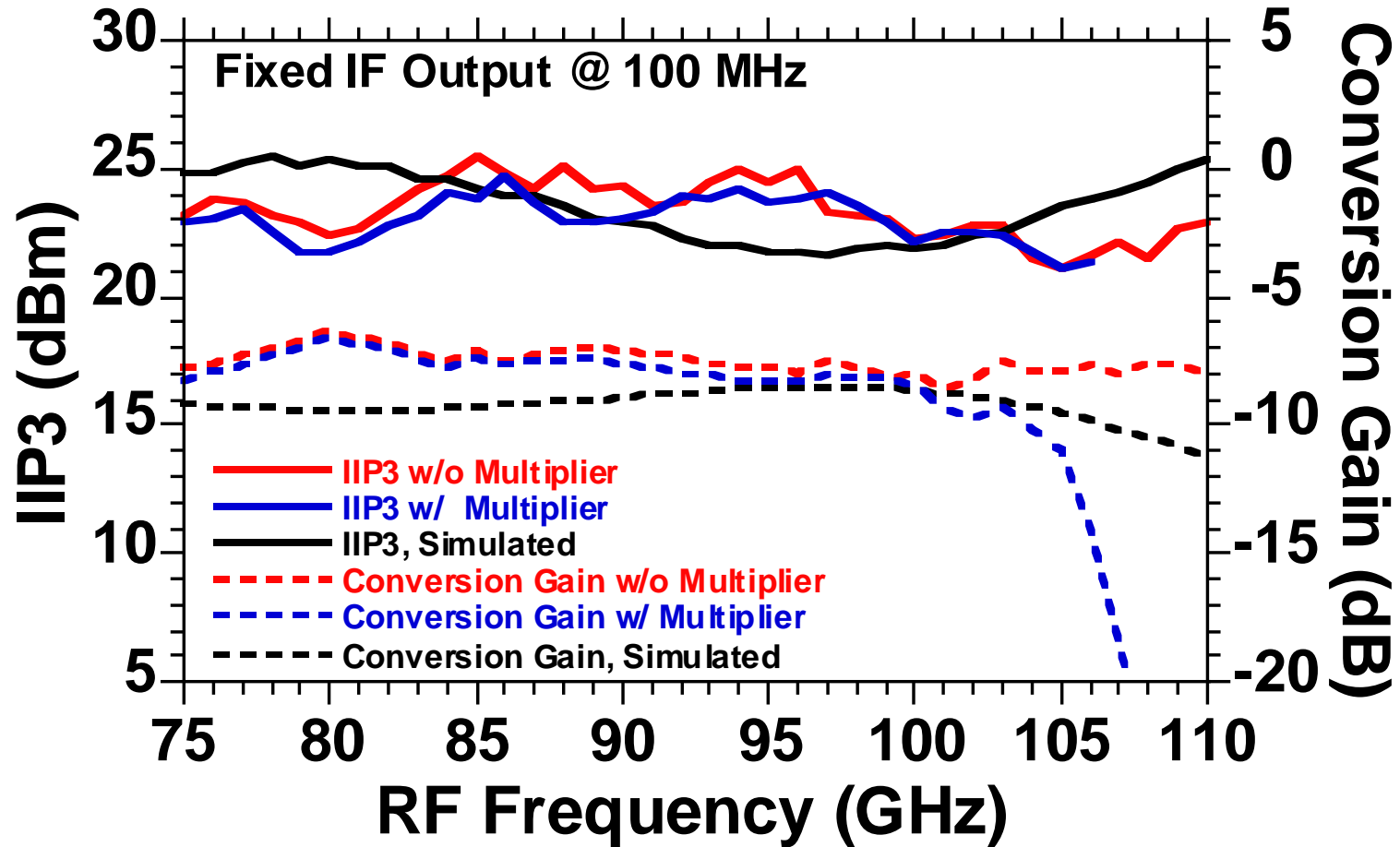
Measurements (UP)



Measurements (UP)



Measurements (Down)



Measurements (Down)

